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(12) **United States Design Patent** (10) **Patent No.: US D684,544 S**
Nagaune (45) **Date of Patent: ** Jun. 18, 2013**

(54) **COOLING JACKET FOR SEMICONDUCTOR DEVICE**

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(73) Assignee: **Fuji Electric Co., Ltd.**, Kanagawa (JP)

(**) Term: **14 Years**

(21) Appl. No.: **29/406,390**

(22) Filed: **Nov. 14, 2011**

(30) **Foreign Application Priority Data**

May 13, 2011 (JP) D2011-010782

(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/179**

(58) **Field of Classification Search**
USPC D13/122, 179, 182; 165/80.2, 80.4, 165/104.19; 361/702
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a cooling jacket for semiconductor device, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of front, top plan and right side of a cooling jacket for semiconductor device showing my new design;

FIG. **2** is a perspective view of rear, bottom and left side thereof;

FIG. **3** is a front view thereof;

FIG. **4** is a rear view thereof;

FIG. **5** is a top plan view thereof;

FIG. **6** is a bottom view thereof;

FIG. **7** is a left side view thereof;

FIG. **8** is a right side view thereof; and,

FIG. **9** is a cross-sectional view thereof taken along line **9-9** in FIG. **9** view.

1 Claim, 7 Drawing Sheets

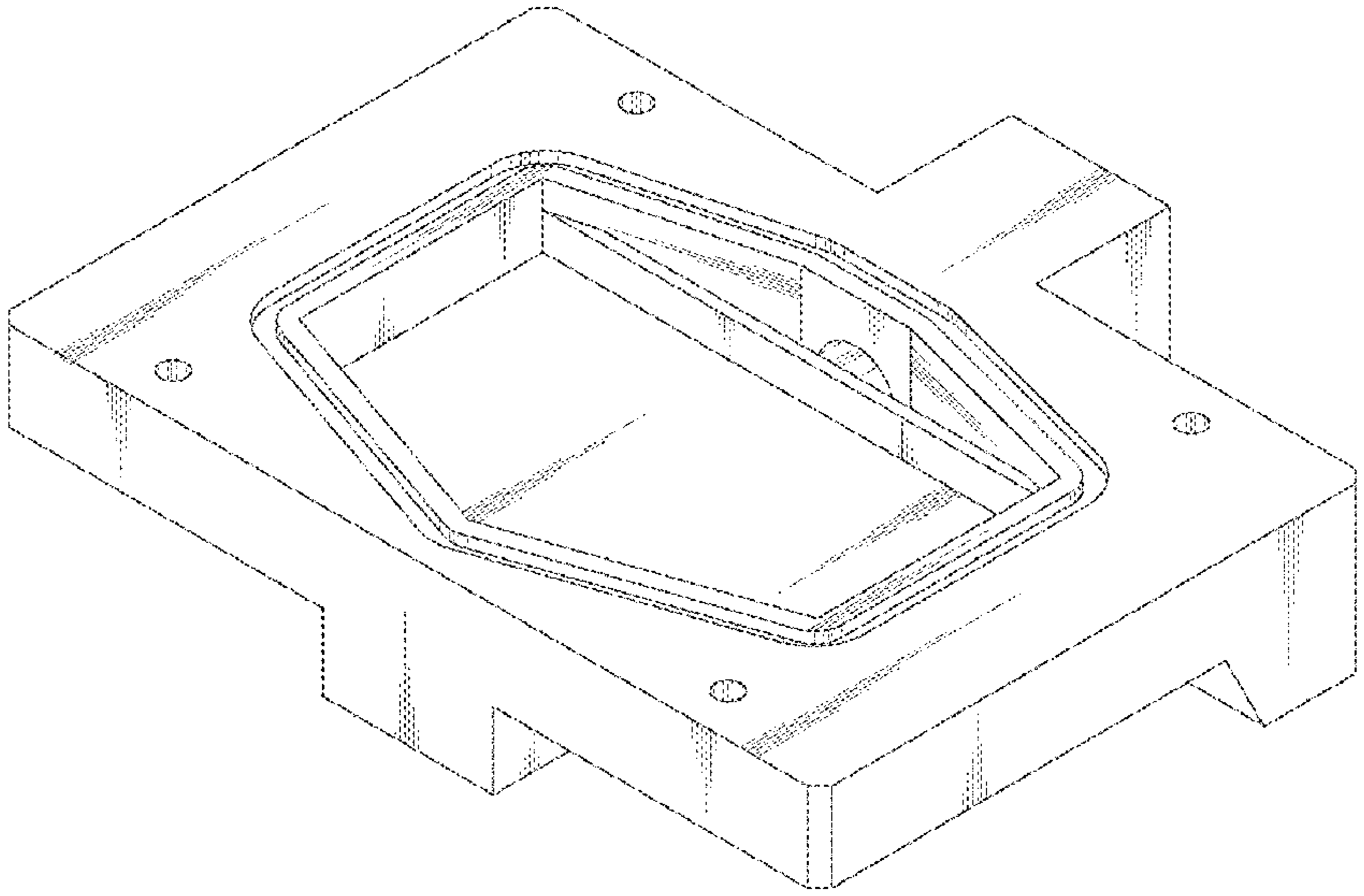

Fig. 1

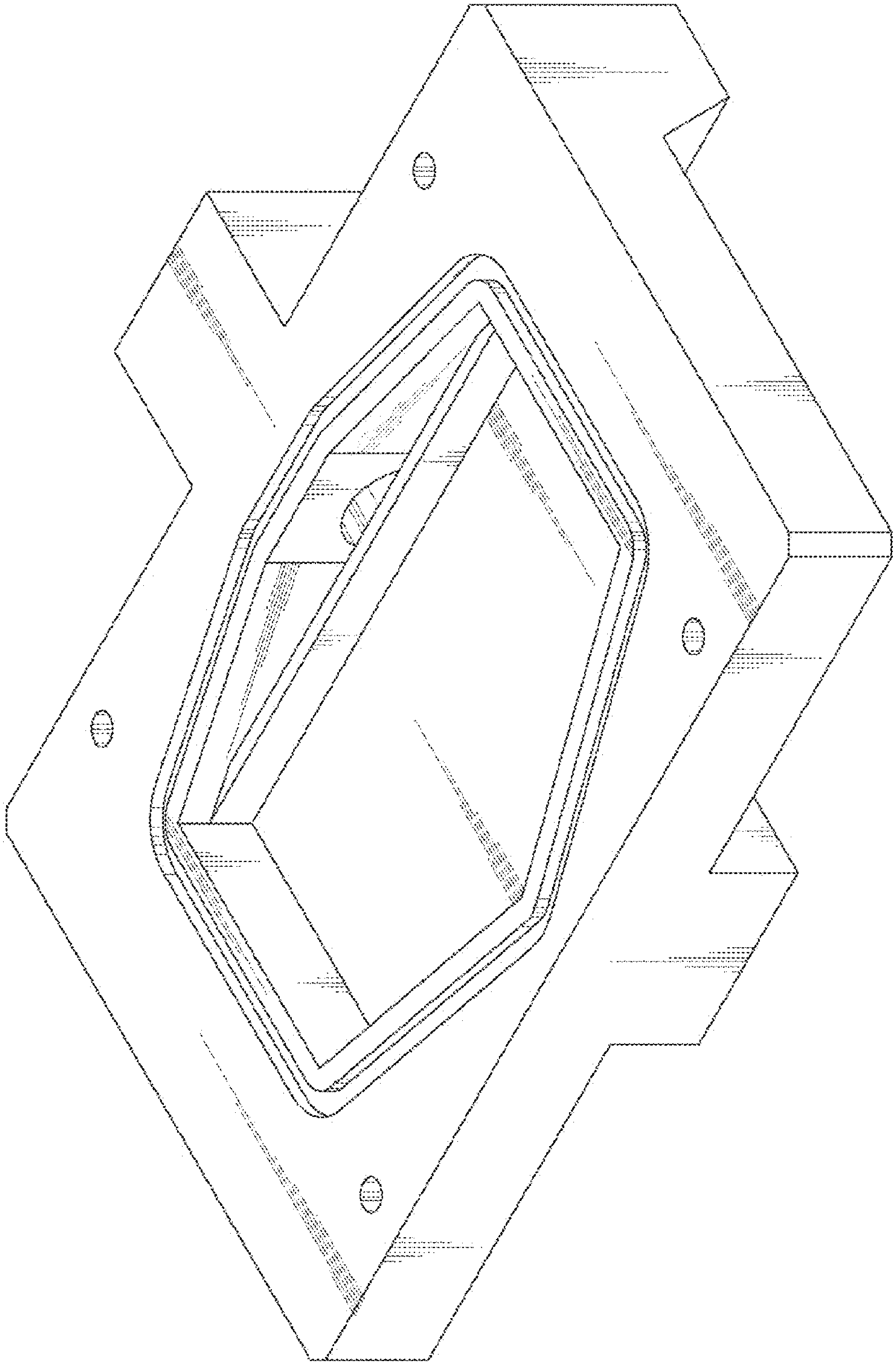

Fig. 2

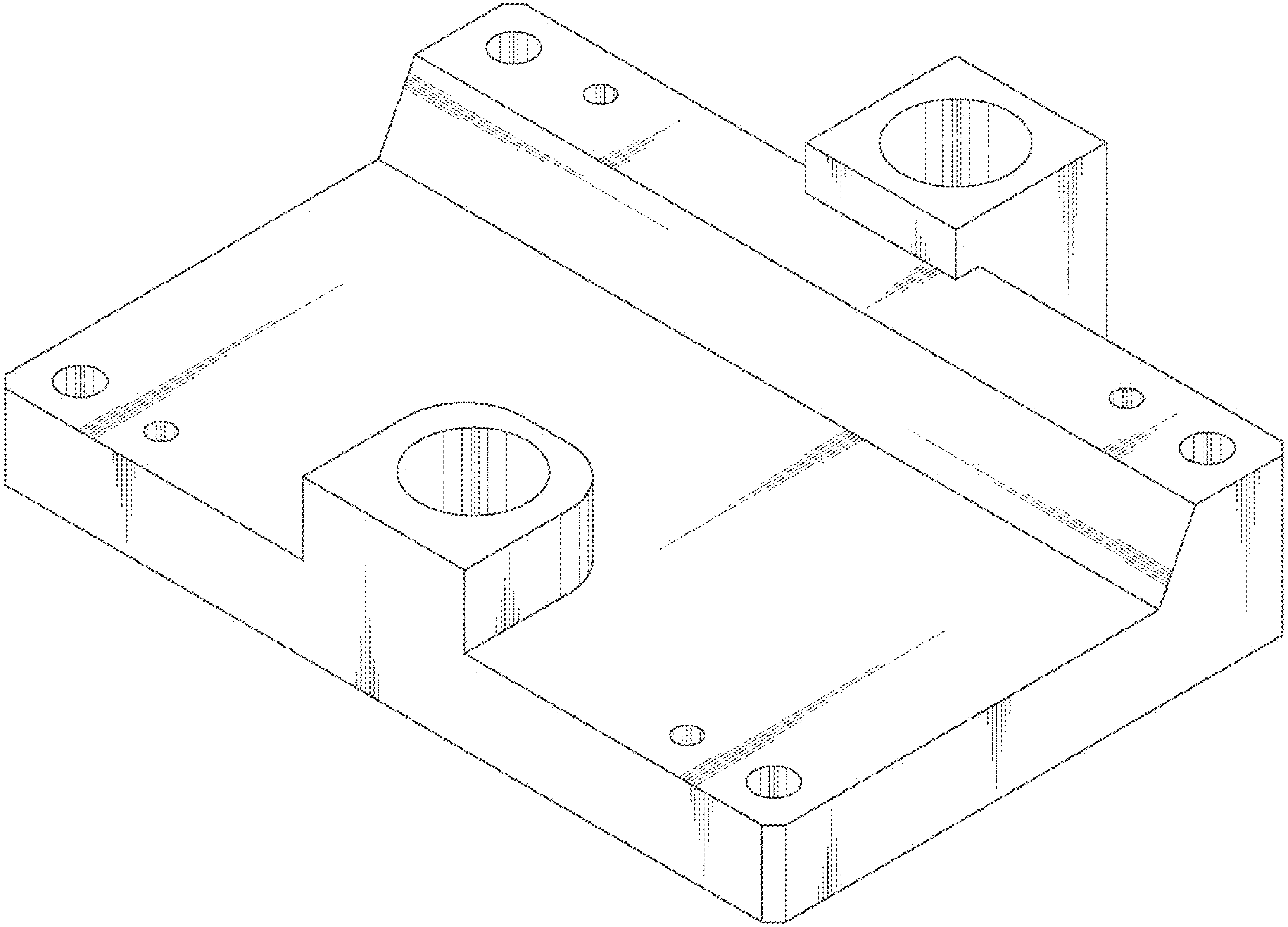

Fig. 3

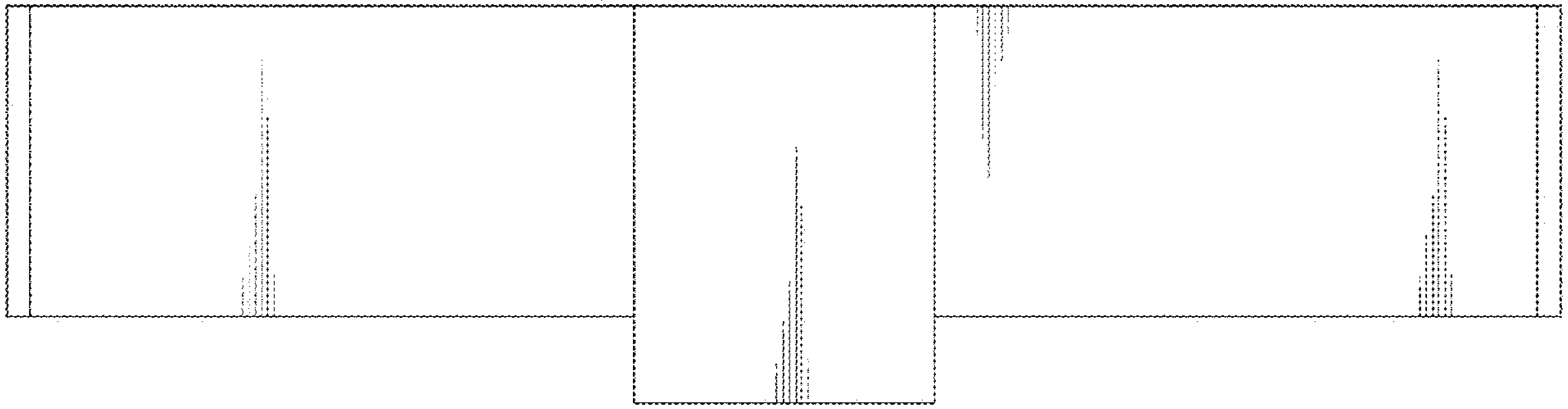

Fig. 4

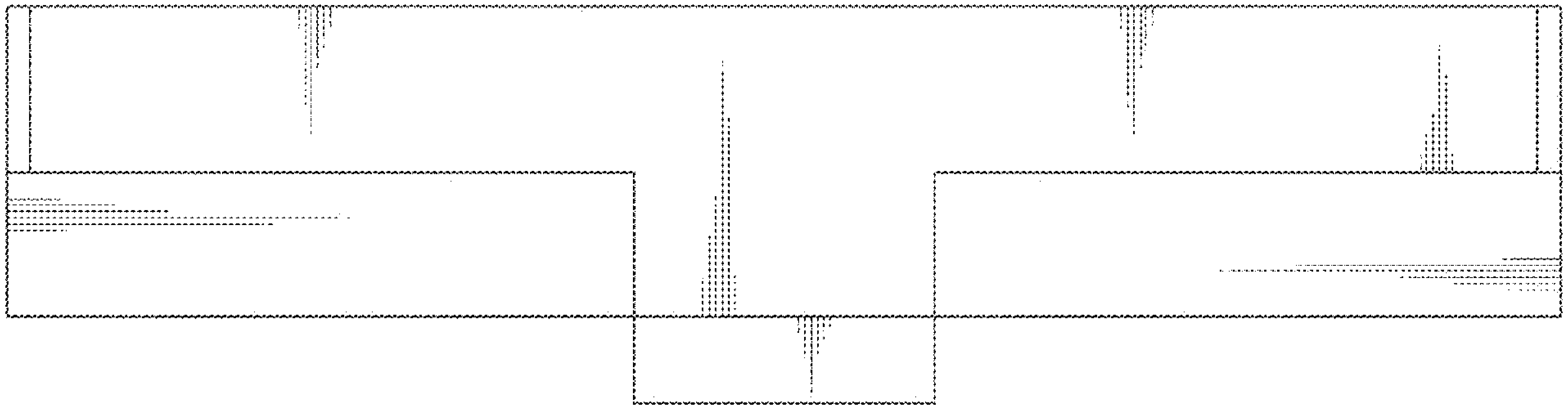

Fig. 5

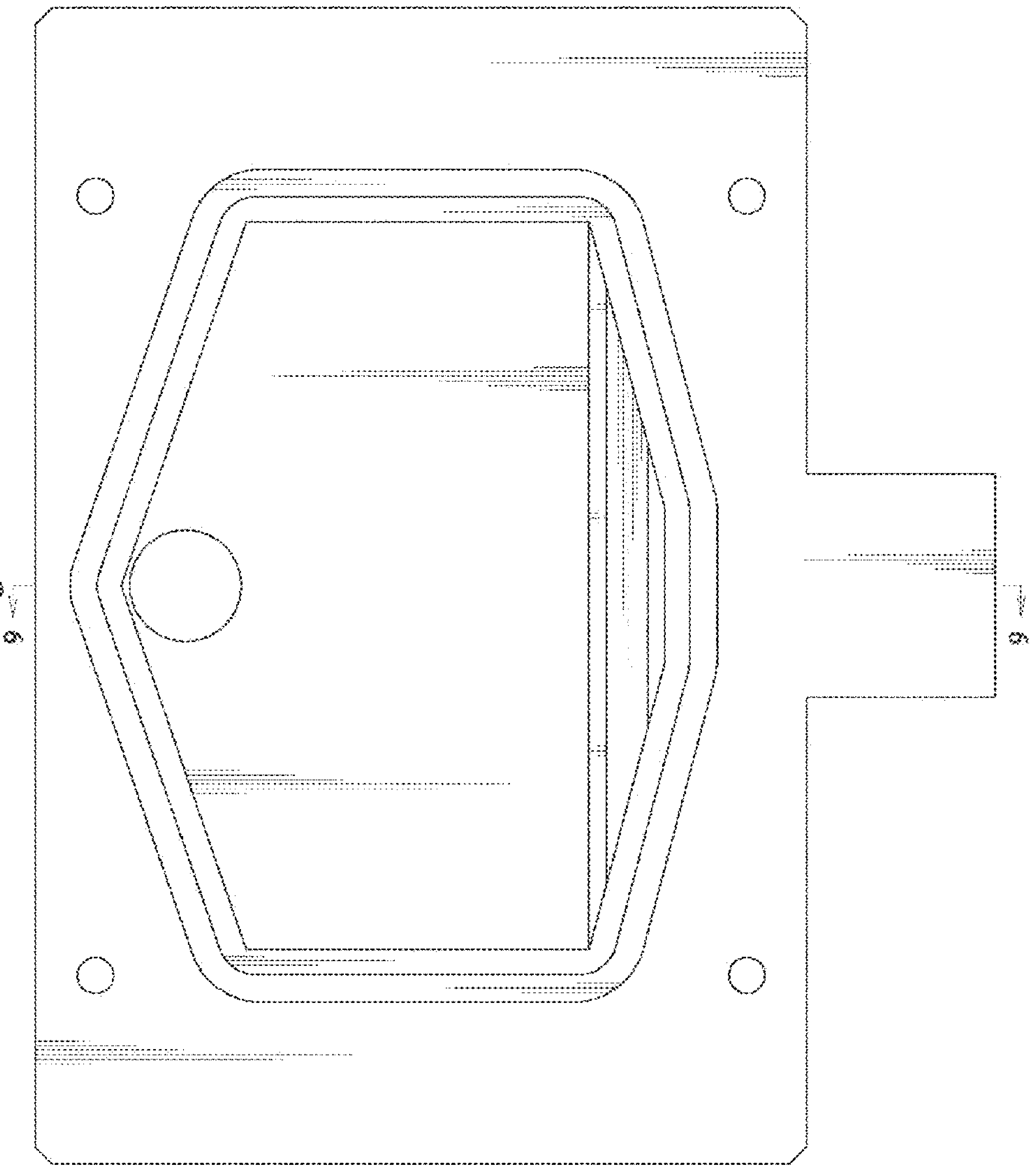

Fig. 6

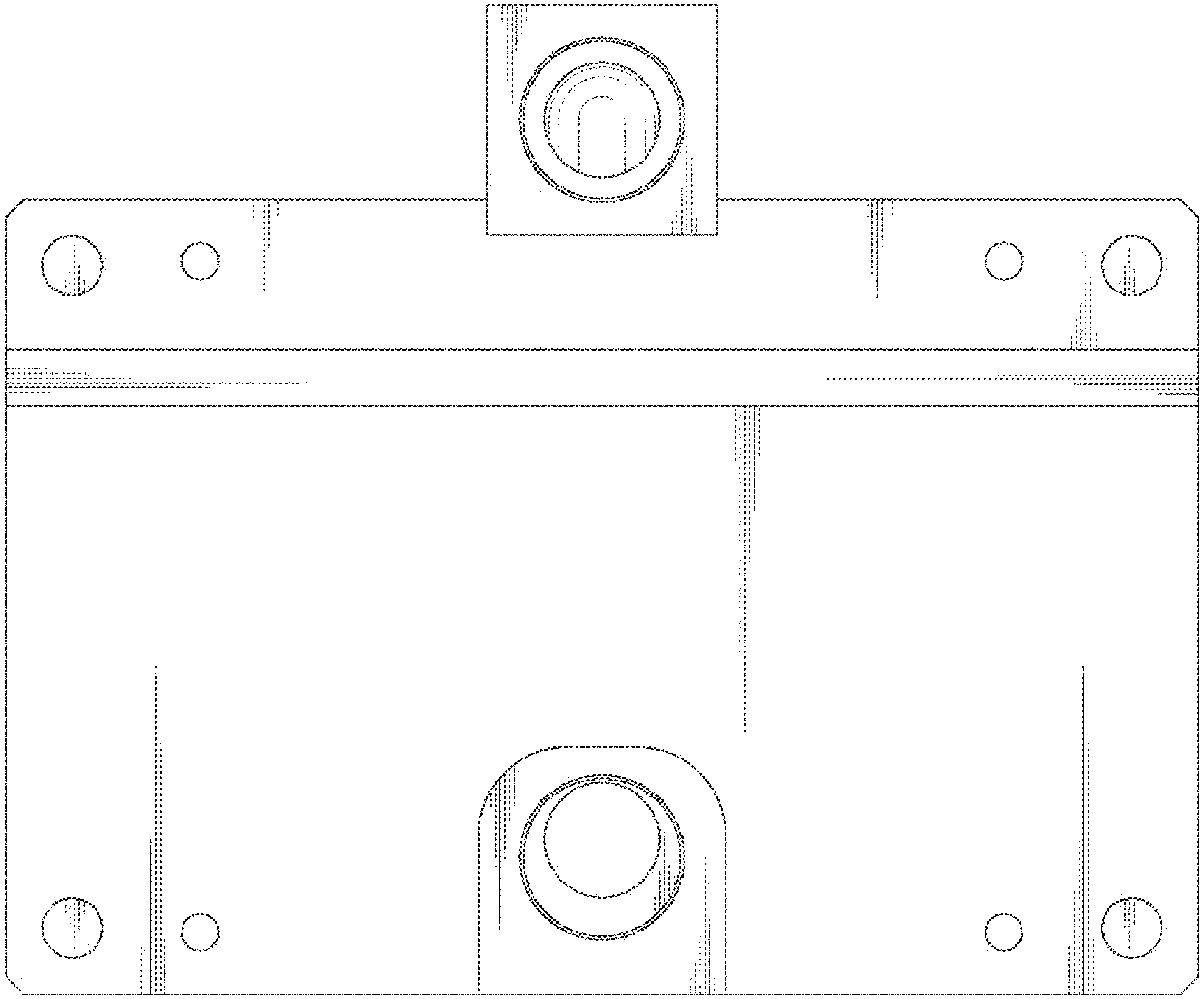

Fig. 7

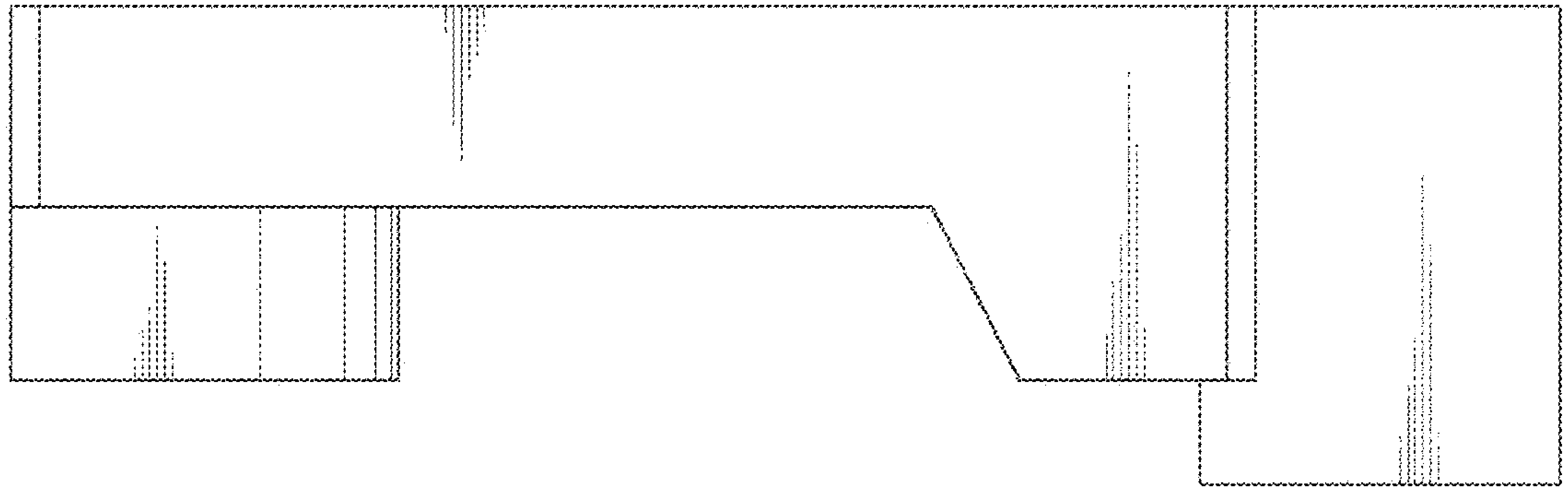

Fig. 8

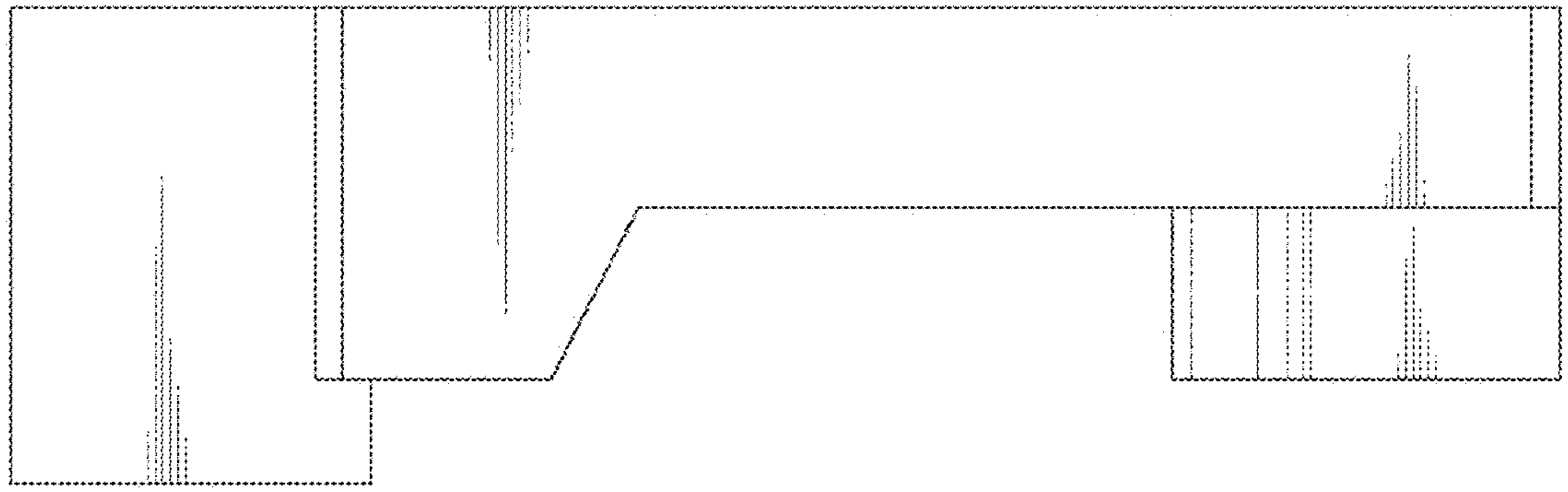

Fig. 9